|  |  |  |  |  |  |  |
| --- | --- | --- | --- | --- | --- | --- |
| **Package** | **Assembly Site** | **Autoclave1**  *121°C, 100%RH, 2 atm, 96 hrs* | **HAST1**  *130C 85%RH 2atm, Biased* | **HTS1**  *150°C, 1000 hrs* | **Temp Cycle1**  *-65°C to 150°C, 500 cycles* | **SHR**  (Solder Heat Resistance) |
| SOIC\_N | Carsem M | Pass | Pass | Pass | Pass | Pass |
|  | **TOTAL**: | 0 fails/1232 samples | 0 fails/ 385 samples | 0 fails/847 samples | 0 fails/1232 samples | 0/366 |

**QUALIFICATION RESULTS: PCN 10\_0356**

1 Parts subjected to preconditioning per J-STD-0020, MSL 1, 3 or 5 with peak reflow temperature of 260°C prior to stress